



## SOLDER-PASTE WETTING TESTER SP-2



SP-2 is wettability testing machine for solder paste, parts electrode and PC board, adopted SP-Tension-Method (Temperature Profile Method)

### Feature

- Can test and evaluate solder paste, PC board and parts-lead.
- All wetting process can be observed from glass windows.
- "Wetting Balance Measuring Method", "Micro-Wetting Balance Measuring Method", and "Quick Heating Method" are possible optionally.
- Can simulate reflow oven profile with hot air and N2 purge.
- Electro-balance sensor adopted allows detection of very small force. The wettability of microchips can now be examined by this unit.
- Analyze wetting time and force with exclusive software.
- Solder wire testing is also available.

### Product specification

Item		Specifications
Load Sensor	Principle	Electro - balance sensor

	<b>Measurement range</b>	10.00gf $\sim$ - 5.00gf
	<b>Measurement accuracy *</b>	$\pm$ (10mgf + 1 digit)
	<b>Resolution</b>	Less than 900 mgf: 0.001 gf More than 900 mgf: 0.005 gf
<b>Temp. Sensor</b>	<b>Measurement range</b>	0 $\sim$ 300 $^{\circ}$ C
	<b>Measurement accuracy</b>	$\pm$ 3 $^{\circ}$ C
<b>Heater unit</b>	<b>Temp. of heater unit</b>	Room temperature $\sim$ 300 $^{\circ}$ C
	<b>O2 Concentration</b>	Simple closed heater unit with nipple for N2 purge test
<b>Temp. profile setting</b>		1. Preheat temp. 2. Preheat time 3. The rate of temp. rise 3 $^{\circ}$ C /sec. (standard) 4. Maximum temp. 5. Maximum temp. time
<b>Melting point</b>		Preset solder paste melting point
<b>Table movement</b>		Automatic: operated by PC Manual: operated by Up/Down switch (selectable 3 steps speed)
<b>Digital output</b>		RS-232C cable (Malcom format)
<b>Air supply</b>		Original air pressure: 0.2 $\sim$ 0.5 Mpa (Approx. 2 $\sim$ 5 kgf / cm <sup>2</sup> ) Adjustment air: 0.2 Mpa (Approx. 2kgf / cm <sup>2</sup> )
<b>Power supply</b>		AC100V 50 / 60Hz 700W
<b>Weight</b>		Approx. 20kg

- **\*Load sensor accuracy is not concerned oscillation.**